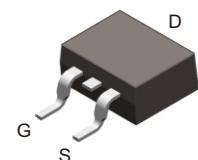


# ACMS35N10D2-HF

**N-Channel  
RoHS Device  
Halogen Free**

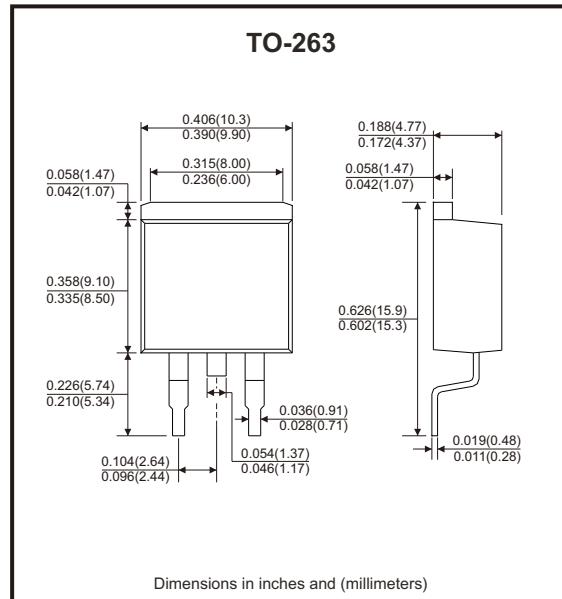


## Features

- Low gate charge minimize switching loss.
- Fast recovery body diode.
- AEC-Q101 Qualified.

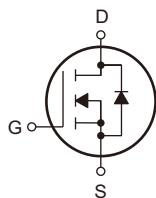
## Mechanical data

- Case: TO-263, molded plastic.
- Molding compound: UL flammability classification rating 94V-0.
- Terminals: Matte tin-plated leads, solderability per MIL-STD-202, method 208.



## Circuit Diagram

- G : Gate
- S : Source
- D : Drain



## Maximum Ratings (at $T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DSS}$	100	V
Gate-source voltage	$V_{GSS}$	$\pm 20$	V
Continuous drain current @ $T_c=25^\circ\text{C}$	$I_D$	35	A
Continuous drain current @ $T_c=100^\circ\text{C}$	$I_D$	25	
Continuous drain current @ $T_A=25^\circ\text{C}$ (Note 1)	$I_D$	9.3	
Continuous drain current @ $T_A=100^\circ\text{C}$ (Note 1)	$I_D$	6.6	
Pulsed drain current ( $t_p = 10\mu\text{s}$ , $T_c=25^\circ\text{C}$ )	$I_{DM}$	175	A
Single pulse avalanche energy (Note 3)	$E_{AS}$	51	mJ
Power dissipation @ $T_c=25^\circ\text{C}$	$P_D$	71	W
Thermal resistance junction to case	$R_{\theta JC}$	2.1	$^\circ\text{C}/\text{W}$
Thermal resistance junction to air (Note 1)	$R_{\theta JA}$	30	$^\circ\text{C}/\text{W}$
Operating junction temperature range	$T_J$	-55 to +175	$^\circ\text{C}$
Storage temperature range	$T_{STG}$	-55 to +175	$^\circ\text{C}$

## Electrical Characteristics (at $T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{DSS}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	100			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 100V, V_{GS} = 0V$			1	$\mu\text{A}$
		$V_{DS} = 80V, V_{GS} = 0V, T_J = 125^\circ\text{C}$			100	
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
<b>On Characteristics</b>						
Drain-source on-resistance (Note 2)	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 14A$			25	$\text{m}\Omega$
	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 14A$			35	$\text{m}\Omega$
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.1	2	2.5	V
Forward threshold voltage	$g_{fs}$	$V_{DS} = 5V, I_D = 15A$		1.5		S
Gate resistance	$R_G$	$V_{GS} = 0V, f = 1\text{MHz}$		1.7		$\Omega$
<b>Dynamic Characteristics</b>						
Input capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 30V, f = 1\text{MHz}$		941		pF
Output capacitance	$C_{oss}$			419		
Reverse transfer capacitance	$C_{rss}$			30		
<b>Switching Characteristics</b>						
Turn-on delay time (Note 4)	$t_{d(on)}$	$V_{DS} = 50V, V_{GS} = 10V$ $R_G = 2.2\Omega, I_D = 14A$		4		ns
Turn-on rise time (Note 4)	$t_r$			19		
Turn-off delay time (Note 4)	$t_{d(off)}$			22		
Turn-off fall time (Note 4)	$t_f$			7		
Total gate charge	$Q_g$	$V_{DS} = 50V, V_{GS} = 10V, I_D = 14A$		19.4		nC
Gate to source charge	$Q_{gs}$			2.7		
Gate to drain (miller) charge	$Q_{gd}$			5.1		
<b>Source-Drain Diode Characteristics</b>						
Diode forward voltage (Note 2)	$V_{SD}$	$I_{SD} = 14A, V_{GS} = 0V$		0.9	1.2	V
Reverse recovery time	$t_{rr}$	$I_{SD} = 14A, V_{GS} = 0V, \frac{dI_{SD}}{dt} = 100A/\mu\text{s}$		40		ns
Reverse recovery charge	$Q_{rr}$			48		nC

- Notes:
1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
  2. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
  3. The EAS data shows Max. rating. The test condition is  $V_{DD}=50V$ ,  $V_{GS}=10V$ ,  $L=0.5\text{mH}$ .
  4. Guaranteed by design, not subject to production.

## Rating and Characteristic Curves (ACMS35N10D2-HF)

Fig.1 - Typical Output Characteristics

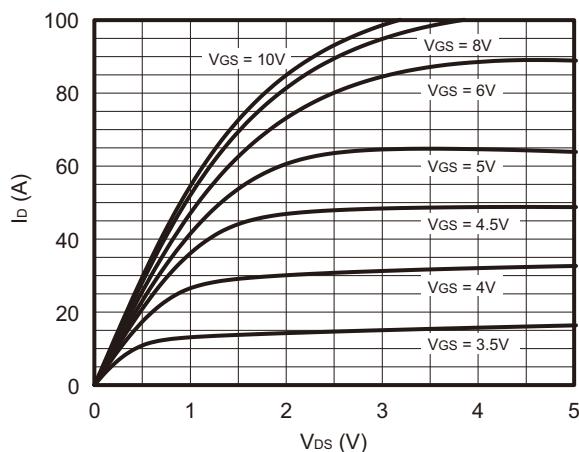


Fig.2 - On-Resistance vs. Drain Current and Gate Voltage

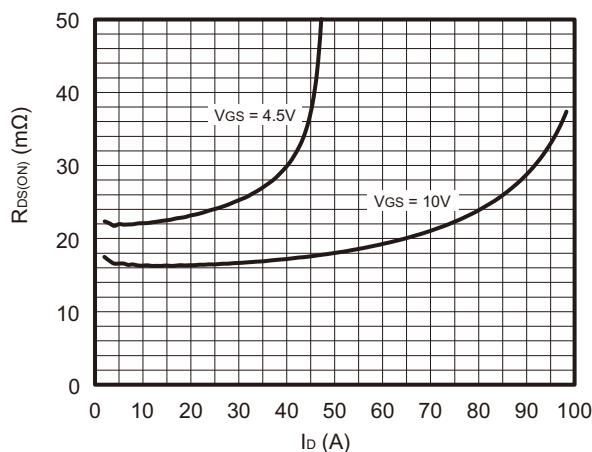


Fig.3 - On-Resistance vs.  $V_{GS}$

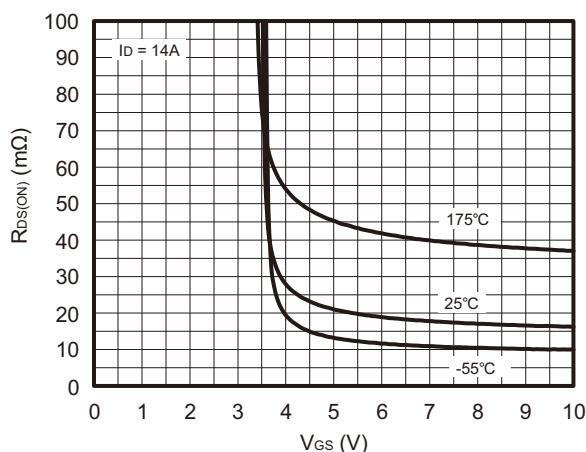


Fig.4 - Body-Diode Characteristics

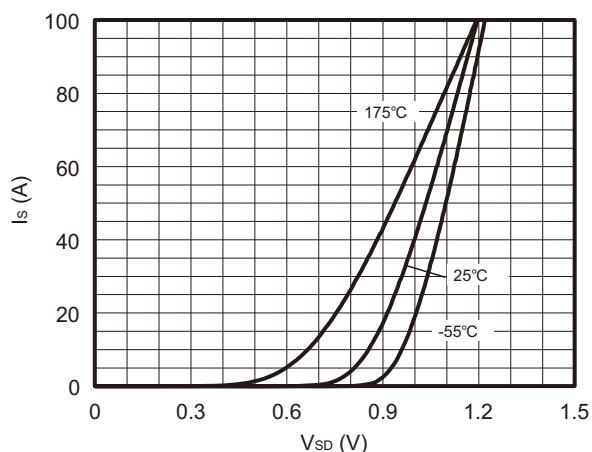


Fig.5 - Normalized On-Resistance vs.  $T_J$

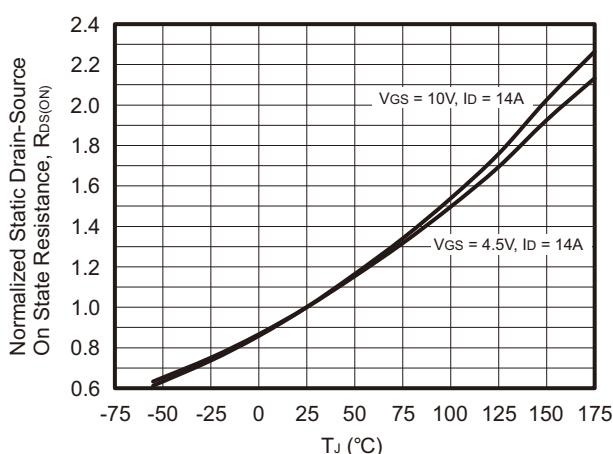
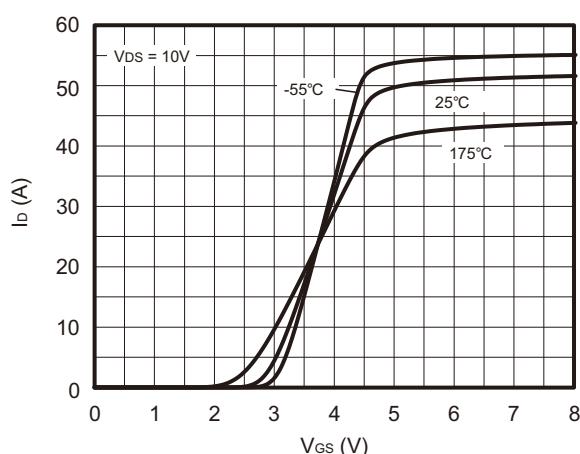


Fig.6 - Transfer Characteristics



## Rating and Characteristic Curves (ACMS35N10D2-HF)

Fig.7 - Capacitance Characteristics

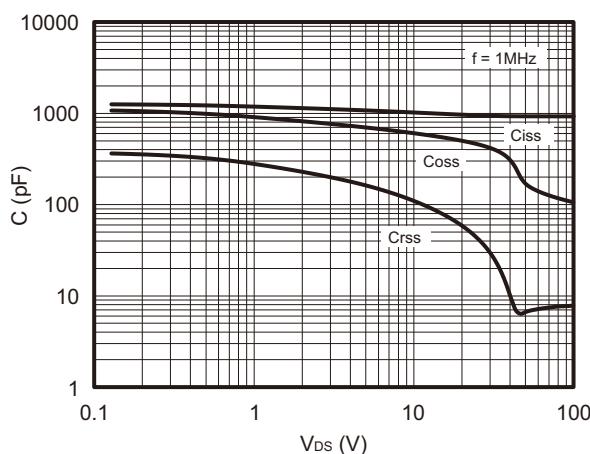


Fig.8 - Gate Charge Characteristics

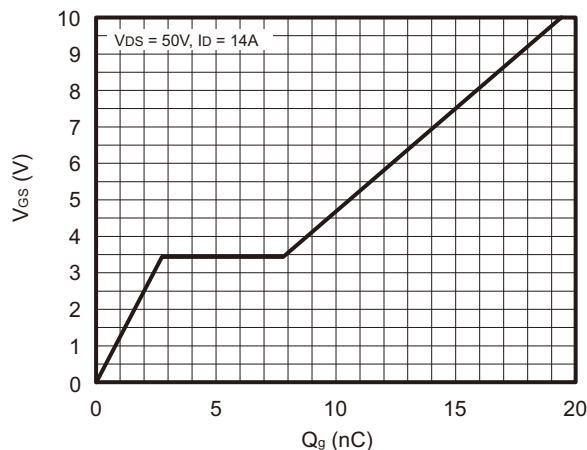


Fig.9 - Normalized Breakdown Voltage vs. T<sub>J</sub>

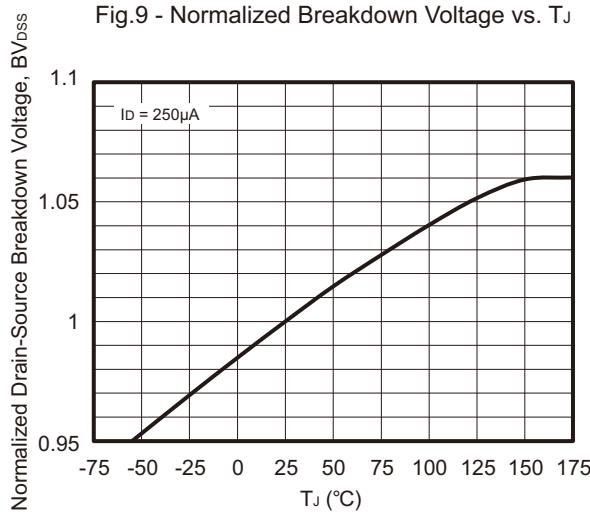


Fig.10 - Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

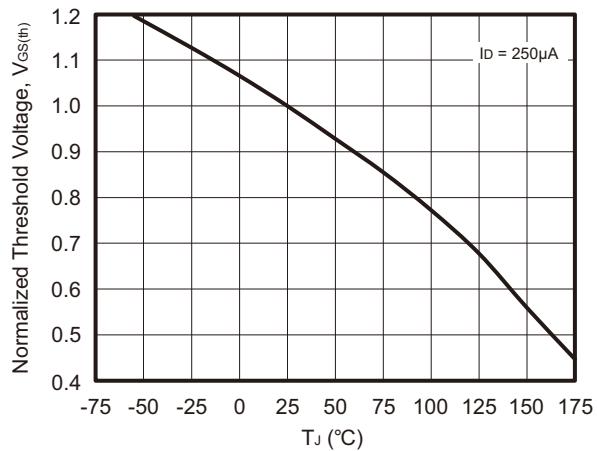
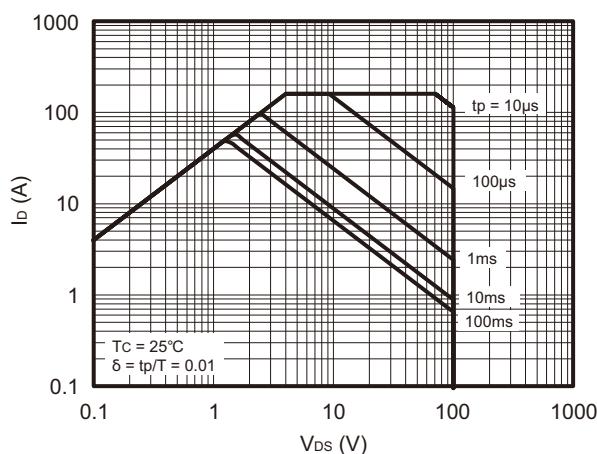
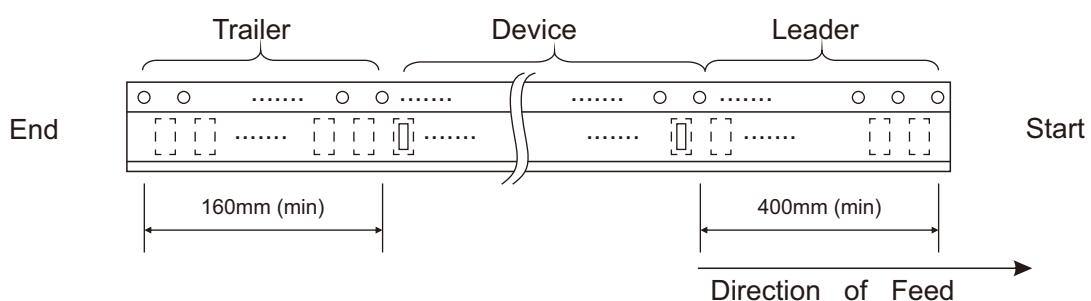
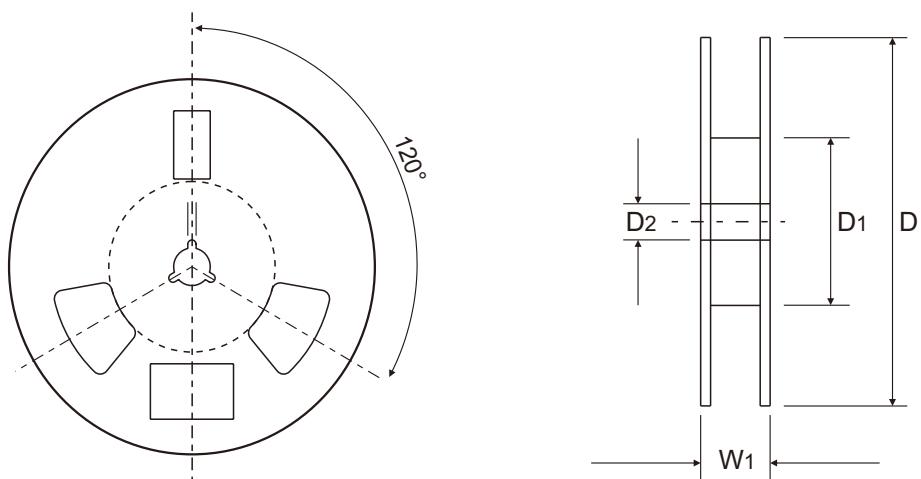
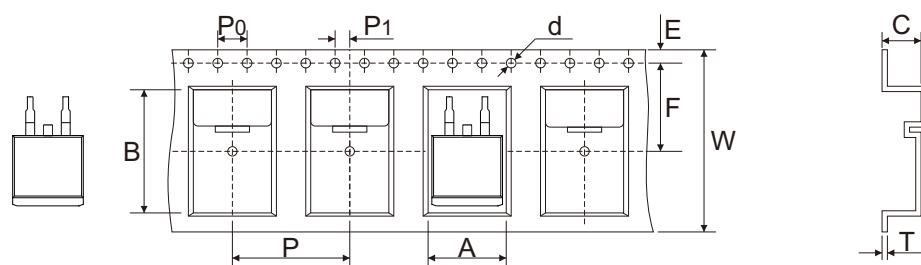


Fig.11 - Safe Operation Area



## Reel Taping Specification

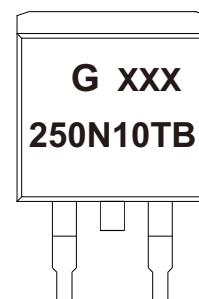


TO-263	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	$10.80 \pm 0.10$	$16.13 \pm 0.10$	$5.21 \pm 0.10$	$1.55 \pm 0.05$	$330 \pm 0.20$	$100 \pm 0.20$	$13.00 \pm 0.20$
	(inch)	$0.425 \pm 0.004$	$0.635 \pm 0.004$	$0.205 \pm 0.004$	$0.061 \pm 0.002$	$12.992 \pm 0.008$	$3.937 \pm 0.008$	$0.512 \pm 0.008$

TO-263	SYMBOL	E	F	P	P0	P1	T	W	W1
	(mm)	$1.75 \pm 0.10$	$11.50 \pm 0.10$	$16.00 \pm 0.10$	$4.00 \pm 0.10$	$2.00 \pm 0.10$	$0.35 \pm 0.03$	$24.00 \pm 0.30$ - 0.10	$24.00 \pm 0.20$
	(inch)	$0.069 \pm 0.004$	$0.453 \pm 0.004$	$0.630 \pm 0.004$	$0.157 \pm 0.004$	$0.079 \pm 0.004$	$0.014 \pm 0.001$	$0.945 \pm 0.012$ - 0.004	$0.945 \pm 0.008$

## Marking Code

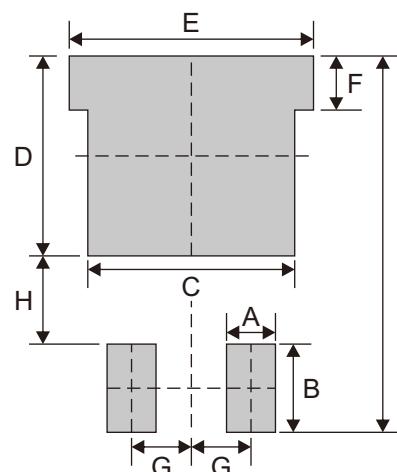
Part Number	Marking Code
ACMS35N10D2-HF	250N10TB



XXX = Control code

## Suggested P.C.B. PAD Layout

SIZE	TO-263	
	(mm)	(inch)
A	2.08	0.110
B	3.50	0.138
C	8.80	0.346
D	9.00	0.354
E	10.4	0.409
F	2.30	0.091
G	2.54	0.100
H	4.00	0.157
I	16.5	0.650



## Standard Packaging

Case Type	REEL PACK	
	REEL (pcs)	Reel Size (inch)
TO-263	800	13